

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Gregory E. Howard and Leland s. Swanson
Serial No.:	To be Determined
Filing Date:	September 10, 2003
Group Art Unit:	Unassigned
Examiner:	Unassigned
Title:	METHOD AND SYSTEM FOR PACKAGING BALL GRID ARRAYS

MAIL STOP PATENT APPLICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

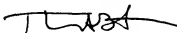
INFORMATION DISCLOSURE STATEMENT

Applicants respectfully request, pursuant to 37 C.F.R. §§1.56, 1.97, and 1.98, that the documents listed on the attached PTO-1449 form be considered and cited in the examination of the above-identified application. A copy of each document is enclosed for the convenience of the Examiner. Furthermore, pursuant to 37 C.F.R. §§1.97(g) and (h), Applicants makes no representation that these documents qualify as prior art or that these documents are material to patentability of the present application or that a search has been made.

Since the present Application was filed after June 30, 2003, a copy of any U.S. Patent and any U.S. Patent Application Publication cited on the attached PTO Form 1449 is not being submitted with this Information Disclosure Statement pursuant to the July 11, 2003 waiver of 37 C.F.R. S 1.98(a)(2)(i) by the U.S. Patent and Trademark Office.

Respectfully submitted,

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Date: September 10, 2003

Customer Number:

05073

Patent Trademark Office

PTO-1449	Application No. To be Assigned		Applicant(s) Howard, et al.	
	Docket Number T1-36332		Group Art Unit To be Assigned	Filing Date Sept. 10, 2003
	(032350.B531)			

U.S. PATENT DOCUMENTS

	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
A						
B						
C						
D						
E						
F						
G						
H						
I						
J						
K						
L						
M						
N						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
O							
P							
Q							

	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
R	"Challenges in High Yield, Fine Pitch Solder Ball Attachment", by Ivy Qin, et al., SEMI - Semicon Singapore - Semiconductor Packaging Conference, pp. 1-10	05/2001
S		
T		

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

U.S. PATENT AND TRADEMARK OFFICE